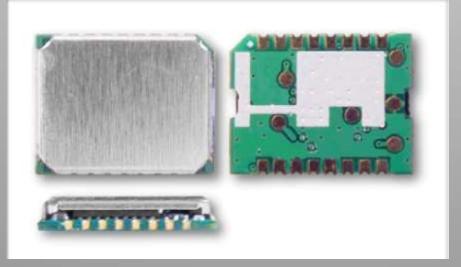
AscenKorea Inc.

AKMU1 GPS Module Datasheet

Revision: V0D



The AKMU1 is a stand-alone GPS module with ultra-high sensitivity (-165dBm) in an ultra-slim form factor (13*10*2.1mm), while utilizing the latest in MediaTek GPS solution.

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AscenKorea Inc.



Title	Ascenkorea AKMU1 Datasheet				
Subtitle	GPS Module				
Doc Type	Datasheet				
Doc Id	GR9804-DS000	C			
Revision	Date	Author	Description		
V0A	2009-10-1	Dennis	First Release		
V0B	2009-10-28	Dennis	Add Reflow Thermal Profile		
V0C	2010-01-28	Dennis	Add Accuracy and RTCM		
V0D	2010-03-23	Dennis	Add Packing and Handling Add SMT and Soldering Warning		



Table of Contents

1. Functional Description	•••••	4
1.1 Overview		
1.2 Highlights and Features		
1.3 System Block Diagram		
2. Specifications		7
2.1 Pin Assignment		
2.2 Description of I/O Pin		
2.3 Specification List		
2.4 Absolute Maximum Ratings		
2.5 Operating Conditions		
3. Protocols		.15
4. Application		
4.1 Description		
4.2 Reference Design Circuit		
5. Packing and Handling		.23
5.1 Moisture Sensitivity		
5.2 Tape Reel Packing Information		
1Kpcs/Reel		
5.3 Storage and Floor Life Guideline		
5.4 Drying		
5.5 ESD Handling		
6. Reflow Soldering Temperature Profile		.28
6.1 SMT Reflow Soldering Temperature Profile:		
6.2 Manual Soldering:		
7. Contact		.31



1. Functional Description

1.1 Overview

The Ascenkorea AKMU1 is a high sensitivity, low power and ultra-slim GPS module.AKMU1 can support up to 66 channels of satellite searching. Even at high speed vehicle movement, AKMU1 has special function to provide maximum update rate 10Hz to give customers more precise position fix and vehicle velocity. It delivers major advancements in GPS performances, accuracy, integration, power consumption and flexibility. It is designed to be suitable for embedded system integration and simplifies the design procedure by module structure. AKMU1 module is the best choice for integrating GPS function into system design.

Application

- ∨ AVL
- ∨ Personal tracker
- ∨ Bike computer
- ∨ Mobile phone
- ∨ PND

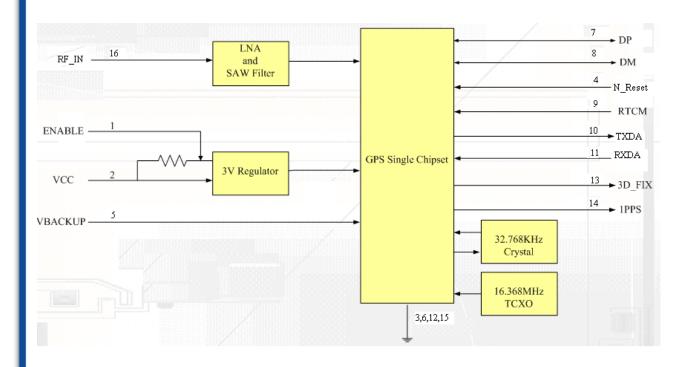


1.2 Highlights and Features

- Ultra-high sensitivity, -165dBm¹
- ◆ L1 Frequency, C/A code, 66-channels satellite searching
- ◆ AGPS support for fast positioning (offline mode: EPO valid up to 14 days)
- ◆ DGPS(WAAS/EGNOS/MSAS/GAGAN) support
- Multi-path detection and compensation
- ◆ E-GSM-900 band rejection
- ◆ E911 compliance
- ◆ USB Interface support
- High update rate, up to 10Hz (configurable by firmware)
- Magnetic Variation function support (configurable by AscenKorea customized firmware)
- Low power consumption, 48mA acquisition, 37mA tracking
- Low shut-down current consumption, 20uA typical
- ◆ Ultra-slim form factor, 13*10*2.1mm
- RoHS compliant

¹ Reference to GPS chipset specification

1.3 System Block Diagram

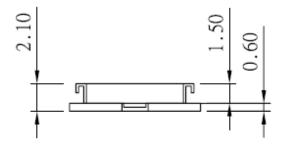


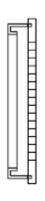


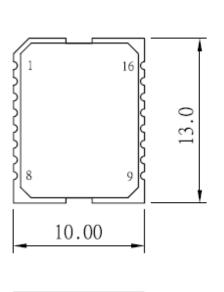
2. Specifications

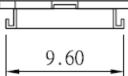
Unit: mm

Mechanical

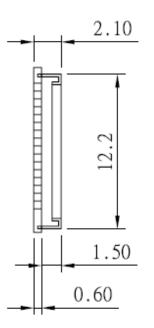








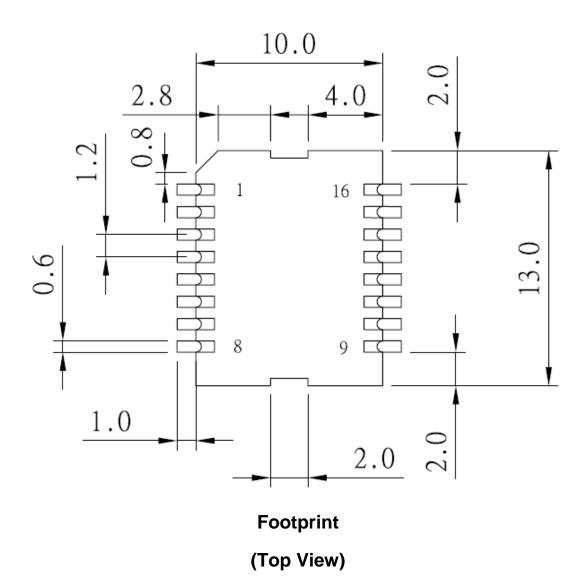
Top View





Unit: mm

Recommend PCB pad Layout





2.1 Pin Assignment

Pin	Name	I/O	Description & Note
1	ENABLE	ı	Keep open or pull high to Power ON
2	VCC	PI	Main DC power input
3	GND	Р	Ground
4	N_Reset	I	Reset Input, Low Active
5	VBACKUP	PI	Backup power input for RTC & navigation data keep
6	GND	Р	Ground
7	DP	I/O	USB port D+
8	DM	I/O	USB port D-
9	RTCM	I	Serial Data Input for DGPS RTCM data streaming
10	TXDA	0	Serial Data Output for NMEA output
11	RXDA	ı	Serial Data Input for Firmware update
12	GND	Р	Ground
13	3D_FIX	0	3D-fix indicator
14	1PPS	0	1PPS Time Mark Output 2.8V CMOS Level
15	GND	Р	Ground
16	RF_IN		Antenna Signal Input



2.2 Description of I/O Pin

ENABLE, Pin1

Keep open or pull high to Power ON. Pull low to shutdown the module.

Enable (High): 1.6V<= V_{enable}<=VCC

Disable (Low): 0V<= V_{enable}<=0.3V

VCC, Pin2

The main DC power supply for the module. The voltage should be kept between from 3.3V to 5.5V. The ripple must be controlled under 50mV_{pp} (Typical: 3.3V)

GND, Pin3

Ground

N_Reset, Pin4

Low active, it causes the module to reset. If not used, keep floating

VBACKUP, Pin5

This is the power for GPS chipset to keep RTC running when main power is removed. The voltage should be kept between 2.0V~4.0V, **Typical 3.0V**

The pin must be wired to power supply for normal operation.



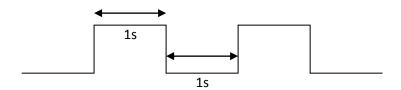
GND, Pin6
Ground
DP, Pin7
USB Port DPLUS signal (Differential Signal +)
DM, Pin8
USB Port DMINUS signal (Differential Signal -)
RTCM, Pin9
This pin receive DGPS data of RTCM protocol (TTL level) ,if not used keep floating
TXDA, Pin10
This is the UART transmitter of the module. It outputs the GPS information for application
RXDA, Pin11
This is the UART receiver of the module. It is used to receive commands from system
GND, Pin12
Ground



3D-FIX, Pin13

The 3D-FIX was assigned as fix flag output. If not used, keep floating

Before 2D Fix
 The pin should continuously output one-second high-level with one-second low-level signal



After 2D or 3D Fix
 The pin should continuously output low-level signal
 Low

1PPS, Pin14

This pin provides one pulse-per-second output from the module, which is synchronized to GPS time. If not used, keep floating; default duration 100ms

GND, Pin15

Ground

RF_IN, Pin16

GPS RF signal input. Patch ; If used to external active antenna, which is the power supply from external DC voltage. The voltage should be kept between 3.0V~4.0V, **Typical 3.0V**



2.3	Spe	ecific	catio	on	List
-----	-----	--------	-------	----	------

2.3 Specification List	
Parameter	Description
GPS Solution	MTK MT3329
Frequency	L1, 1575.42MHz
Sensitivity ¹	Acquisition -148dBm, cold start Reacquisition -160dBm Tracking -165dBm
Channel	66 channels
TTFF ¹	Hot start: 1 second typical Warm start: 33 seconds typical Cold start: 35 seconds typical
Position Accuracy	Without aid:3.0m 2D-RMS DGPS(RTM,SBAS(WAAS,EGNOS,MSAS)):2.5m 2D-RMS
Velocity Accuracy	Without aid : 0.1m/s DGPS(RTM,SBAS(WAAS,EGNOS,MSAS)):0.05m/s
Acceleration Accuracy	Without aid: 0.1 m/s ² DGPS(RTM,SBAS(WAAS,EGNOS,MSAS)):0.05m/s ²
Timing Accuracy (1PPS output)	100 ns RMS
Altitude	Maximum 18,000m (60,000 feet)
Velocity	Maximum 515m/s (1000 knots)
Acceleration	Maximum 4G
Update Rate	1Hz (default), maximum 10Hz
Baud Rate	9600 bps (default)
DGPS	RTCM protocol(configurable by firmware) or SBAS(defult) [WAAS, EGNOS, MSAS,GAGAN]
AGPS	Support
Power Supply	VCC: 3.3V to 5.5V; VBACKUP: 2.0V to 4.0V
Current Consumption	48mA acquisition, 37mA tracking
Current Consumption	Shut-down current consumption 20uA typical
Working Temperature	-40 °C to +85 °C
Dimension	13x10x2.1m, SMD
Weight	0.5g

¹ Reference to GPS chipset specification



2.4 Absolute Maximum Ratings

The voltage applied for VCC should not exceed 6VDC;

Parameter	Symbol	Min.	Тур.	Max.	Unit
Power Supply Voltage	VCC	_	3.3	5.5	V
Backup battery Voltage	VBACKUP	2.0	3.0	4.0	V

2.5 Operating Conditions

Parameter	Condition	Min.	Тур.	Max.	Unit
Operation supply Ripple Voltage	_	_	_	50	mVpp
RX0 TTL H Level	VCC=3.3V	2.1	_	VCC	V
RX0 TTL L Level	VCC=3.3V	0	_	0.9	٧
TX0 TTL H Level	VCC=3.3V	2.1	_	2.8	V
TX0 TTL L Level	VCC=3.3V	0	_	0.8	V
RTCM TTL H Level	VCC=3.3V	2.1	_	VCC	V
USB D+	Standard	_	_	_	V
USB D-	Standard	_	_	_	٧
RTCM TTL L Level	VCC=3.3V	0	_	0.9	V
Current Consumption @ 3.3V	Acquisition	43	48	53	mA
	Tracking	32	37	42	mA
Backup Power Consumption@ 3.0V	25 ℃	_	20	_	uA



3. Protocols

NMEA Output Sentence

Table-1 lists each of the NMEA output sentences specifically developed and defined by MTK for use within MTK products

Table-1: NMEA Output Sentence					
Option	Description				
GGA	Time, position and fix type data.				
GSA	GPS receiver operating mode, active satellites used in the position solution and DOP values.				
GSV	The number of GPS satellites in view satellite ID numbers, elevation, azimuth, and SNR values.				
RMC	Time, date, position, course and speed data. Recommended Minimum Navigation Information.				
VTG	Course and speed information relative to the ground.				



GGA—Global Positioning System Fixed Data. Time, Position and fix related data

Table-2 contains the values for the following example:

\$GPGGA,064951.000,2307.1256,N,12016.4438,E,1,8,0.95,39.9,M,17.8,M,,*65

Table-2: GGA Data Format						
Name	Example	Units	Description			
Message ID	\$GPGGA		GGA protocol header			
UTC Time	064951.000		hhmmss.sss			
Latitude	2307.1256		ddmm.mmmm			
N/S Indicator	N		N=north or S=south			
Longitude	12016.4438		dddmm.mmmm			
E/W Indicator	Е		E=east or W=west			
Position Fix	1		See Table-3			
Indicator						
Satellites Used	8		Range 0 to 14			
HDOP	0.95		Horizontal Dilution of Precision			
MSL Altitude	39.9	meters	Antenna Altitude above/below mean-sae-level			
Units	M	meters	Units of antenna altitude			
Geoidal Separation	17.8	meters				
Units	M	meters	Units of geoid separation			
Age of Diff. Corr.		second	Null fields when DGPS is not used			
Checksum	*65					
<cr> <lf></lf></cr>			End of message termination			

Table-3: Position Fix Indicator				
Value	Description			
0	Fix not available			
1	GPS fix			
2	Differential GPS fix			

GSA—GNSS DOP and Active Satellites

Table-4 contains the values for the following example:

\$GPGSA,A,3,29,21,26,15,18,09,06,10,,,,,2.32,0.95,2.11*00

	Table-4: GSA Data Format						
Name	Example	Units	Description				
Message ID	\$GPGSA		GSA protocol header				
Mode 1	Α		See Table-5				
Mode 2	3		See Table-6				
Satellite Used	29		SV on Channel 1				
Satellite Used	21		SV on Channel 2				
Satellite Used			SV on Channel 12				
PDOP	2.32		Position Dilution of Precision				
HDOP	0.95		Horizontal Dilution of Precision				
VDOP	2.11		Vertical Dilution of Precision				
Checksum	*00						
<cr> <lf></lf></cr>			End of message termination				

Table-5: Mode 1			
Value	Description		
M	Manual—forced to operate in 2D or 3D mode		
А	2D Automatic—allowed to automatically switch 2D/3D		

Table-6: Mode 2				
Value	Description			
1	Fix not available			
2	2D (<4 SVs used)			
3	3D (≧4 SVs used)			



GSV—GNSS Satellites in View

Table-7 contains the values for the following example:

\$GPGSV,3,1,09,29,36,029,42,21,46,314,43,26,44,020,43,15,21,321,39*7D

\$GPGSV,3,2,09,18,26,314,40,09,57,170,44,06,20,229,37,10,26,084,37*77 \$GPGSV,3,3,09,07,,,26*73

Table-7: GSV Data Format						
Name	Example	Units	Description			
Message ID	\$GPGSV		GSV protocol header			
Number of Messages	3		Range 1 to 3 (Depending on the number of satellites tracked, multiple messages of GSV data may be required.)			
Message Number1	1		Range 1 to 3			
Satellites in View	09					
Satellite ID	29		Channel 1 (Range 1 to 32)			
Elevation	36	degrees	Channel 1 (Maximum 90)			
Azimuth	029	degrees	Channel 1 (True, Range 0 to 359)			
SNR (C/No)	42	dBHz	Range 0 to 99, (null when not tracking)			
Satellite ID	15		Channel 4 (Range 1 to 32)			
Elevation	21	degrees	Channel 4 (Maximum 90)			
Azimuth	321	degrees	Channel 4 (True, Range 0 to 359)			
SNR (C/No)	39	dBHz	Range 0 to 99, (null when not tracking)			
Checksum	*7D					
<cr> <lf></lf></cr>			End of message termination			



RMC—Recommended Minimum Navigation Information

Table-8 contains the values for the following example:

\$GPRMC,064951.000,A,2307.1256,N,12016.4438,E,0.03,165.48,260406,,,A*55

Table-8: RMC Data Format				
Name	Example	Units	Description	
Message ID	\$GPRMC		RMC protocol header	
UTC Time	064951.000		hhmmss.sss	
Status	Α		A=data valid or V=data not valid	
Latitude	2307.1256		ddmm.mmmm	
N/S Indicator	N		N=north or S=south	
Longitude	12016.4438		dddmm.mmmm	
E/W Indicator	Е		E=east or W=west	
Speed over Ground	0.03	knots		
Course over Ground	165.48	degrees	True	
Date	260406		ddmmyy	
Magnetic Variation		degrees	E=east or W=west (Need Ascenkorea Customization Service)	
Mode	А		A= Autonomous mode D= Differential mode E= Estimated mode	
Checksum	*65			
<cr> <lf></lf></cr>			End of message termination	



VTG—Course and speed information relative to the ground

Table-9 contains the values for the following example:

\$GPVTG,165.48,T,,M,0.03,N,0.06,K,A*37

Table-9: VTG Data Format					
Name	Example	Units	Description		
Message ID	\$GPVTG		VTG protocol header		
Course	165.48	degrees	Measured heading		
Reference	T		True		
Course		degrees	Measured heading		
Reference	M		Magnetic		
			(Need Ascenkorea		
			Customization Service)		
Speed	0.03	knots	Measured horizontal speed		
Units	N		Knots		
Speed	0.06	km/hr	Measured horizontal speed		
Units	K		Kilometers per hour		
Mode	Α		A= Autonomous mode		
			D= Differential mode		
			E= Estimated mode		
Checksum	*06				
<cr> <lf></lf></cr>			End of message termination		

MTK NMEA Command Protocol

Packet Type:

103 PMTK_CMD_COLD_START

Packet Meaning:

Cold Start: Don't use Time, Position, Almanacs and Ephemeris data at re-start.

Example:

\$PMTK103*30<CR><LF>



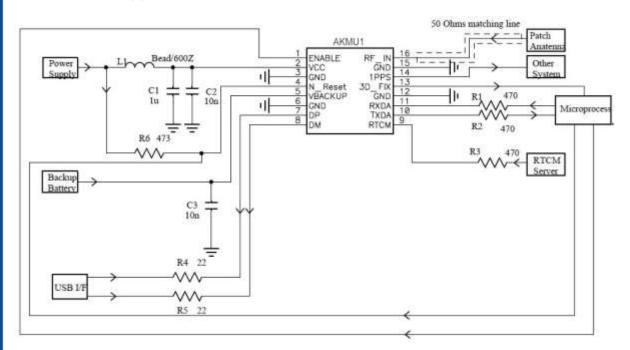
4. Application

4.1 Description

This chapter introduces the reference schematic design for the best performance.

4.2 Reference Design Circuit

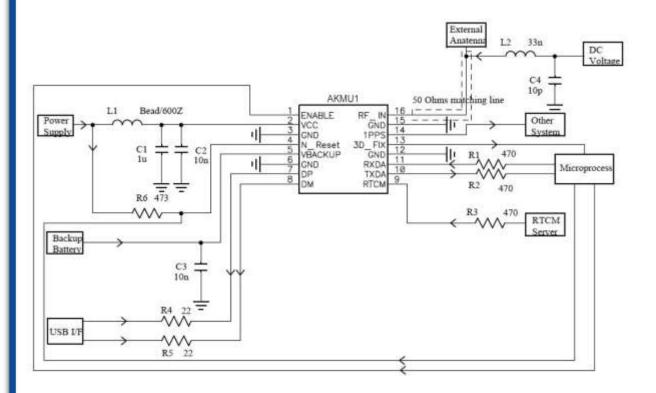
Patch Antenna Application



Notice:

- 1. Ferrite bead L1 was add for power noise reduction.
- 2. C1 and C2 decoupling capacitor should put near module. For C1, the value depends on system noise, range 1uF~100uF is reasonable.
- 3. Damping resistors R1, R2, R3, R4 and R5 should be fine-tuned for system application.

External Antenna Application



Notice:

- 1. Ferrite bead L1 was add for power noise reduction.
- 2. C1 and C2 decoupling capacitor should put near module. For C1, the value depends on system noise, range 1uF~100uF is reasonable.
- 3. Damping resistors R1, R2, R3, R4 and R5 should be fine-tuned for system application.
- 4. L2 was added for RF Choke.
- 5. C4 was added for power noise reduction.



5. Packing and Handling

GPS modules, like any other SMD devices, are sensitive to moisture, electrostatic discharge, and temperature. By following the standards outlined in this document for AscenKorea GPS module storage and handling, it is possible to reduce the chances of them being damaged during production set-up. This document will go through the basics on how AscenKorea packages its modules to ensure they arrive at their destination without any damages and deterioration to performance quality, as well as some cautionary notes before going through the surface mount process.



Please read the sections II to V carefully to avoid damages permanent damages due to moisture intake



GPS receiver modules contain highly sensitive electronic circuits and are electronic sensitive devices and improper handling without ESD protections may lead to permanent damages to the modules. Please read section VI for more details.

5.1 Moisture Sensitivity

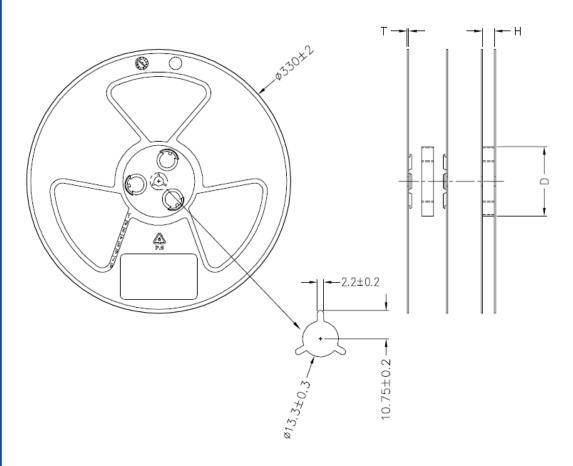
AscenKorea GPS modules are moisture sensitive, and must be pre-baked before going through the solder reflow process. It is important to know that:

AscenKorea GPS modules must complete solder reflow process in 72 hours after pre-baking.

This maximum time is otherwise known as "Floor Life"

If the waiting time has exceeded 72 hours, it is possible for the module to suffer damages during the solder reflow process such as cracks and delamination of the SMD pads due to excess moisture pressure.

5.2 Tape Reel Packing Information 1Kpcs/Reel



Spec: H: 24.5±1.5, T:2.2±0.2, D:99±1.5

Note: 13"Reel, Material: P.S

Unit: (mm)

Figure 1: Reel Dimension

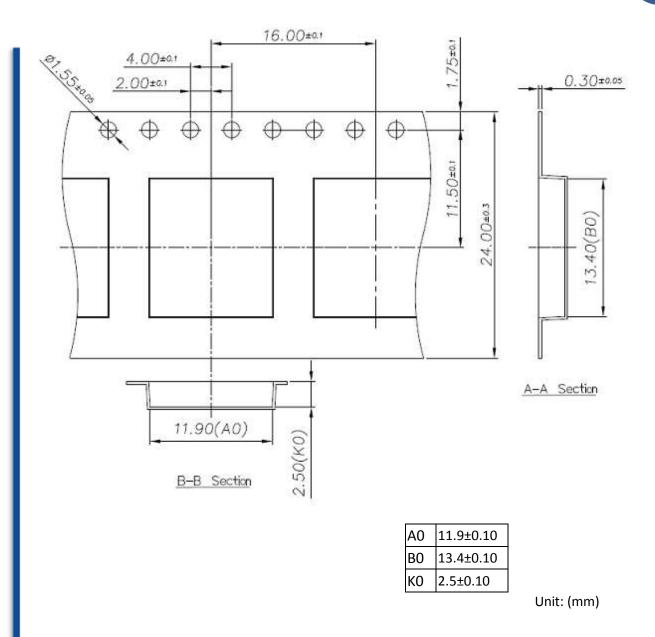


Figure 2: Tape Dimension

The moisture color coded card provides an insight to the relative humidity percentage (RH). When the GPS modules are taken out, it should be around or lower than 30% RH level.

Outside each electrostatic bag is a caution label for moisture sensitive device.



Caution

This bag contains MOISTURE-SENSITIVE & ELECTROSTATIC SENSITIVE DEVICES



- Calculated shelf life in package bag: 6 months at < 30 °C and < 60% relative humidity (RH)
 - Temperature and Humidity must be controlled in SMT production line and storage area. Temperature of 23 °C, 60% +/-5% RH humidity is highly recommended. (please refer to IPQC for more information)
- Devices require bake before mounting and subjected to reflow solder
- After baking, devices that will be subjected to reflow solder or other high temperature process must be mounted within 72 hours of factory conditions ≤ 30°C/60% RH
- Peak package body temperature: 250 +0 /-5 °C
 - The reflow temperature and its profile data must be measured before the SMT process and match the levels and guidelines set by IPQC.
 - When performing solder paste printing please check if the amount of solder paste is in excess or insufficient, as both conditions may lead to defects such as electrical shortage, empty solder and etc.
 - c. The usage of solder paste should follow "first in first out" principle. Opened solder paste needs to be monitored and recorded in a timely fashion (Please refer to IPQC for more info).





Figure 3: Example of moisture color coded card and caution label



5.3 Storage and Floor Life Guideline

Since AscenKorea modules must undergo solder-reflow process in 72 hours after it has gone through pre-baking procedure, therefore if it is not used by then, it is recommended to store the GPS modules in dry places such as dry cabinet.

The approximate shelf life for AscenKorea GPS modules packages is 6 months from the bag seal date, when store in a non-condensing storage environment (<30°C/60% RH)



It is important to note that it is a required process for AscenKorea GPS modules to undergo pre-baking procedures, regardless of the storage condition.

5.4 Drying

Because the vapor pressures of moisture inside the GPS modules increase greatly when it is exposed to high temperature of solder reflow, in order to prevent internal delaminating, cracking of the devices, or the "popcorn" phenomenon, it is a necessary requirement for AscenKorea GPS module to undergo pre-baking procedure before any high temperature or solder reflow process.

The recommendation baking time for AscenKorea GPS module is as follows:

√ 60°C for 8 to 12 hours

Once baked, the module's floor life will be "reset", and has additional 72 hours in normal factory condition to undergo solder reflow process.



A Please limit the number of times the GPS modules undergoes baking processes as repeated baking process has an effect of reducing the wetting effectiveness of the SMD pad contacts. This applies to all SMT devices.



Oxidation Risk: Baking SMD packages may cause oxidation and/or intermetallic growth of the terminations, which if excessive can result in solderability problems during board assembly. The temperature and time for baking SMD packages are therefore limited by solderability considerations. The cumulative bake time at a temperature greater than 90°C and up to 125°C shall not exceed 96 hours. Bake temperatures higher than 125°C are now allowed.



5.5 ESD Handling



Please carefully follow the following precautions to prevent severe damage to GPS modules.

AscenKorea GPS modules are sensitive to electrostatic discharges, and thus are Electrostatic Sensitive Devices (ESD). Careful handling of the GPS modules and in particular to its patch antenna (if included) and RF_IN pin, must follow the standard ESD safety practices:

- ✓ Unless there is a galvanic coupling between the local GND and the PCB GND, then the first point of contact when handling the PCB shall always be between the local GND and PCB GND.
- ✓ Before working with RF IN pin, please make sure the GND is connected
- ✓ When working with RF_IN pin, do not contact any charges capacitors or materials that can easily develop or store charges such as patch antenna, coax cable, soldering iron.
- ✓ Please do not touch the mounted patch antenna to prevent electrostatic discharge from the RF input
- ✓ When soldering RF IN pin, please make sure to use an ESD safe soldering iron (tip).

✓

6. Reflow Soldering Temperature Profile

The following reflow temperature profile was evaluated by Ascenkorea and has been proven to be reliable qualitatively. Please contact us beforehand if you plan to solder this component using a deviated temperature profile as it may cause significant damage to our module and your device.

All the information in this sheet can only be used only for Pb-free manufacturing process.

6.1 SMT Reflow Soldering Temperature Profile:

(Reference Only)

Average ramp-up rate (25 ~ 150°C): 3°C/sec. max.

Average ramp-up rate (270°C to peak): 3°C/sec. max.

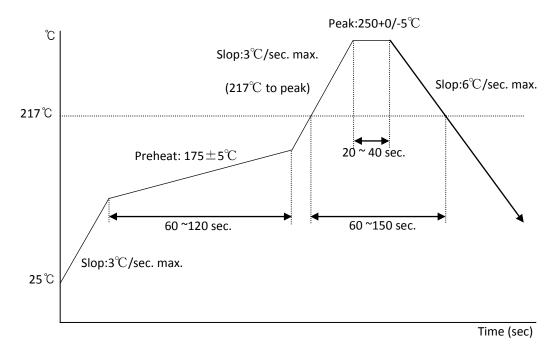
Preheat: 175 ± 25°C, 60 ~ 120 seconds

Temperature maintained above 217°C: 60~150 seconds

Peak temperature: 250 +0/-5°C, 20~40 seconds

Ramp-down rate: 6°C/sec. max.

Time 25°C to peak temperature: 8 minutes max.



Notes:

- 1. Module must be pre-baked **before** going through SMT solder reflow process.
- The usage of solder paste should follow "first in first out" principle. Opened solder paste needs to be monitored and recorded in a timely fashion (can refer to IPQC for related documentation and examples).
- 3. Temperature and humidity must be controlled in SMT production line and storage area. Temperature of 23°C, 60±5% RH humidity is recommended. (please refer to IPQC for related documentation and examples)



- 4. When performing solder paste printing, please notice if the amount of solder paste is in excess or insufficient, as both conditions may lead to defects such as electrical shortage, empty solder and etc.
- The reflow temperature and its profile data must be measured before the SMT process and match the levels and guidelines set by IPQC.

6.2 Manual Soldering:

Soldering iron:

Bit Temperature: Under 380°C Time: Under 3 sec.

Notes:

- 1. Please do not directly touch the soldering pads on the surface of the PCB board, in order to prevent further oxidation
- The solder paste must be defrosted to room temperature before use so it can return to its optimal working temperature. The time required for this procedure is unique and dependent on the properties of the solder paste used.
- 3. The steel plate must be properly assessed before and after use, so its measurement stays strictly within the specification set by SOP.
- 4. Please watch out for the spacing between soldering joint, as excess solder may cause electrical shortage
- 5. Please exercise with caution and do not use extensive amount of flux due to possible siphon effects on neighboring components, which may lead to electrical shortage.
- 6. Please do not use the heat gun for long periods of time when removing the shielding or inner components of the GPS module, as it is very likely to cause a shift to the inner components and will leads to electrical shortage.



7. Contact

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